



**【3. 定格及び適用電線 RATINGS AND APPLICABLE WIRES】**

| 項目<br>Item   | 規格<br>Standard  |   |
|--|---|---|
| 最大許容電圧<br>Rated Voltage (MAX.)   | 125 V(実効値 rms)  |   |
| 最大許容電流<br>及び適用電線<br>Rated Current (MAX.)<br>and Applicable wires   | AWG. #26  | 1.0 A   |
|  | AWG. #28  | 1.0 A   |
|  | AWG. #30  | 1.0 A   |
|  | AWG. #32  | 0.8 A   |
| 使用温度範囲 <sup>*1*2*3</sup><br>Ambient Temperature Range  | -40°C ~ +105°C<br>低温において氷結しないこと Not freeze in low temperature |   |
| 防湿梱包開梱後の推奨保管条件 <sup>*4</sup><br>Storage condition after opening<br>the Humidity Prevention package<br>53261-**71/53261-**27<br>53398-**71に適用 | 温度<br>Temperature   | -5°C~+35°C  |
|  | 湿度<br>Humidity  | 70%R.H.以下(但し結露なきこと)<br>70%R.H.MAX.(No condensation) |

- \*1: 基板実装後の無通電状態は、使用温度範囲が適用されます。  
Non-operating connectors after reflow must follow the operating temperature range condition.
- \*2: 通電による温度上昇分も含む。 Including terminal temperature rise.
- \*3: 適合電線も本使用温度範囲を満足すること。  
Applicable wires must also meet the specified temperature range.
- \*4: 開梱後の取り扱いについては、本書の取り扱いの注意事項を参照下さい。  
Refer to 【Instruction upon usage】.

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| <b>T</b>                               | REVISE ON PC ONLY | TITLE:<br><br>PicoBlade 1.25 WIRE TO BOARD<br>SMT CONNECTOR<br><br><b>製品仕様書</b>   |
|  | SEE SHEET 1 OF 17 |   |
| REV.                                   | DESCRIPTION       | THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC<br>TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION |
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参考許容電流 CURRENT DERATING REFERENCE INFORMATION

| AWG | 2-circuits | 8-circuits | 15-circuits |
|-----|------------|------------|-------------|
|     | Amps (A)   | Amps (A)   | Amps (A)    |
| 26  | 2.5        | 1.5        | 1.0         |
| 28  | 2.0        | 1.5        | 1.0         |
| 30  | 1.5        | 1.0        | 1.0         |
| 32  | 1.5        | 1.0        | 0.8         |

- 1) 各電流値は参考となります。  
Values are for REFERENCE ONLY
- 2) 閾値は温度上昇30°C以下としています。  
Current deratings are based on not exceeding 30° C Temperature Rise.
- 3) 温度上昇の測定は圧着端子のバレル部にて実施しています。  
Temperature Rise is measured in barrel area of crimp terminal.
- 4) 基板デザインにより温度上昇の結果が異なります。  
PCB trace design can greatly affect temperature rise results.
- 5) 全極に通電し測定しています。  
Data is for all circuits powered.

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**【4. 性能 PERFORMANCE】**

**4-1. 電気的性能 ELECTRICAL PERFORMANCE**

| 項目<br>Item  | 条件<br>Test Condition  | 規格<br>Requirement   |
|---|---|---------------------|
| 4-1-1<br>接触抵抗<br>Contact Resistance                       | コネクタを嵌合させ、開放電圧 20mV以下、短絡電流 10mA 以下にて測定する。(JIS C5402-2-1)<br><br>Mate connectors and measured by dry circuit, 20mV MAX., 10mA.MAX.<br>(JIS C5402-2-1)  | 20 milliohm MAX.    |
| 4-1-2<br>絶縁抵抗<br>Insulation Resistance                    | コネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、DC 500V を印加し測定する。<br>(JIS C5402-3-1/MIL-STD-202 試験法 302)<br>Apply 500V DC between adjacent terminals or terminal and ground.<br>(JIS C5402-3-1/MIL-STD-202 Method 302)                          | 100 Megohm MIN.     |
| 4-1-3<br>耐電圧<br>Dielectric Strength                       | コネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、AC 250V (実効値)を 1分間 印加する。<br>(JIS C5402-4-1/MIL-STD-202 試験法 301)<br>Apply 250V AC(rms) between adjacent terminals or terminal and ground for 1 minute.<br>(JIS C5402-4-1/MIL-STD-202 Method 301) | 異常無きこと<br>No Damage |
| 4-1-4<br>圧着部接触抵抗<br>Contact Resistance on Crimped Portion | ターミナルに適合電線を圧着し、開放電圧20mV以下、短絡電流 10mA 以下にて測定する。<br><br>Crimp the applicable wire to the terminal, measured by dry circuit, 20mV MAX., 10mA.MAX.   | 5 milliohm MAX.     |

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4-2. 機械的性能 MECHANICAL PERFORMANCE

| 項 目<br>Item |  | 条 件<br>Test Condition   | 規 格<br>Requirement            |                    |
|-------------|--|---|-------------------------------|--------------------|
| 4-2-1       | 挿入力<br>及び抜去力<br>Insertion and<br>Withdrawal<br>Force | 毎分 25±3mm の速さで挿入、抜去を行う。<br>Insert and withdraw connectors at the speed rate of 25±3mm/minute.   | 第9項参照<br>Refer to paragraph 9 |                    |
| 4-2-2       | 圧着部引張強度<br>Crimping<br>Pull out Force                | 圧着されたターミナルを治具に固定し、電線を軸方向に毎分25±3mmの速さで引張る。<br>(JIS C5402-16-4)<br><br>Fix the crimped terminal to the jig, apply axial pull out force on the wire at the speed rate of 25±3 mm/minute.<br>(JIS C5402-16-4) | AWG. #26                      | 9.8 N{1.0kgf} MIN. |
|             |  |   | AWG. #28                      | 9.8 N{1.0kgf} MIN. |
|             |  |   | AWG. #30                      | 4.9 N{0.5kgf} MIN. |
|             |  |   | AWG. #32                      | 3.0 N{0.3kgf} MIN. |
| 4-2-3       | 圧着端子挿入力<br>Crimp Terminal<br>Insertion Force         | 圧着されたターミナルをハウジングに挿入する。<br>Insert the crimped terminal into the housing.   | 4.9 N{0.5kgf} MAX.            |                    |
| 4-2-4       | 圧着端子保持力<br>Crimp Terminal<br>Retention Force         | ハウジングに装着した圧着されたターミナルを毎分 25±3mm の速さで引張る。<br>Apply axial pull out force at the speed rate of 25±3 mm/minute on the crimped terminal assembled in the housing.   | 4.9 N{0.5kgf} MIN.            |                    |
| 4-2-5       | HDR端子保持力<br>Header Terminal<br>Retention Force       | ハウジングに装着されたターミナルを毎分25±3mm の速さで軸方向に引張る。<br>Apply axial pull out force at the speed rate of 25±3mm/minute on the terminal assembled in the housing.   | 4.9 N{0.5kgf} MIN.            |                    |

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4-3. その他 OTHERS

| 項 目<br>Item |   | 条 件<br>Test Condition   | 規 格<br>Requirement               |                         |
|-------------|---|---|----------------------------------|-------------------------|
| 4-3-1       | 繰り返し挿抜<br>Repeated<br>Insertion /<br>Withdrawal | 1分間10回以下の速さで、挿入、抜去を30回 繰返す。<br>Insert and withdraw connectors 30 cycles repeatedly by rate of less than 10 cycles per minute.   | 接 触 抵 抗<br>Contact<br>Resistance | 40 milliohm<br>MAX.     |
| 4-3-2       | 温度上昇<br>Temperature<br>Rise                     | コネクタを嵌合させ、全ての圧着端子を直列に接続し最大許容電流で熱平衡に達した時の温度上昇を測定する。(UL498)<br>Mate connectors and all crimp terminals shall be connected in a direct series.<br>The temperature rise shall be measured when the terminal reaches terminal equilibrium allowable current.<br>(UL498)  | 温 度 上 昇<br>Temperature<br>Rise   | 30°C MAX.               |
| 4-3-3       | 耐振動性<br>Vibration                               | コネクタを嵌合させ、DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な 3方向に 掃引割合 10~55~10 Hz/分、全振幅 1.5mm の振動を各2時間 加える。(ケーブルは固定すること)<br>(JIS C 60068-2-6/MIL-STD-202 試験法 201)<br>Mate connectors and subject to the following vibration conditions, for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1mA during the test.<br>(Fix the cable at test.)<br>Amplitude : 1.5mm P-P<br>Frequency : 10~55~10 Hz in 1 minute.<br>Duration : 2 hours in each X.Y.Z.axes.<br>(JIS C 60068-2-6/MIL-STD-202 Method 201) | 外 観<br>Appearance                | 異常無きこと<br>No Damage     |
|             |   |   | 接 触 抵 抗<br>Contact<br>Resistance | 40 milliohm<br>MAX.     |
|             |   |   | 瞬 断<br>Discontinuity             | 1.0 microsecond<br>MAX. |

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| 項 目<br>Item |                          | 条 件<br>Test Condition  | 規 格<br>Requirement            |                         |
|-------------|--------------------------|--|-------------------------------|-------------------------|
| 4-3-4       | 耐衝撃性<br>Mechanical Shock | コネクタを嵌合させ、DC 1mA 通電状態にて、テストパルス半周期、嵌合軸を含む互いに垂直な6方向に490m/s <sup>2</sup> { 50G }、作用時間11msの衝撃を各3回、合計18回加える。<br>(JIS C60068-2-27/MIL-STD-202 試験法 213)<br>Mate connectors and subject to the following shock conditions. 3 shocks shall be applied along 3 mutually perpendicular axes, passing DC 1 mA current during the test.<br>(Total of 18 shocks)<br>Test pulse : Half Sine<br>Peak value : 490 m/s <sup>2</sup> (50 G)<br>Duration : 11 ms<br>(JIS C60068-2-27/MIL-STD-202 Method 213) | 外 観<br>Appearance             | 異常無きこと<br>No Damage     |
|             |                          |  | 接 触 抵 抗<br>Contact Resistance | 40 milliohm<br>MAX.     |
|             |                          |  | 瞬 断<br>Discontinuity          | 1.0 microsecond<br>MAX. |
| 4-3-5       | 耐熱性<br>Heat Resistance   | コネクタを嵌合させ、85±2°C の雰囲気中に96時間放置後取り出し、1~2時間室温に放置する。<br>(JIS C60068-2-2/MIL-STD-202 試験法 108)<br>Mate connectors and expose to 85±2°C for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours , after which the specified measurements shall be performed.<br>(JIS C60068-2-2/MIL-STD-202 Method 108)   | 外 観<br>Appearance             | 異常無きこと<br>No Damage     |
|             |                          |  | 接 触 抵 抗<br>Contact Resistance | 40 milliohm<br>MAX.     |
| 4-3-6       | 耐寒性<br>Cold Resistance   | コネクタを嵌合させ、-40±3°C の雰囲気中に96時間 放置後取り出し、1~2時間 室温に放置する。(JIS C60068-2-1)<br><br>Mate connectors and expose to -40±3°C for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>(JIS C60068-2-1)   | 外 観<br>Appearance             | 異常無きこと<br>No Damage     |
|             |                          |  | 接 触 抵 抗<br>Contact Resistance | 40 milliohm<br>MAX.     |

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| 項 目<br>Item |                               | 条 件<br>Test Condition   | 規 格<br>Requirement               |                                 |
|-------------|-------------------------------|---|----------------------------------|---------------------------------|
| 4-3-7       | 耐湿性<br>Humidity               | コネクタを嵌合させ、60±2°C、相対湿度90~95%の雰囲気中に96時間放置後取り出し、1~2時間 室温に放置する。<br>(JIS C60068-2-78/MIL-STD-202 試験法 103)<br><br>Mate connectors and expose to 60±2°C, relative humidity 90 to 95% for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>(JIS C60068-2-78/MIL-STD-202 Method 103)   | 外 観<br>Appearance                | 異常無きこと<br>No Damage             |
|             |                               |   | 接 触 抵 抗<br>Contact Resistance    | 40 milliohm MAX.                |
|             |                               |   | 耐 電 圧<br>Dielectric Strength     | 4-1-3項を満たすこと<br>Must meet 4-1-3 |
|             |                               |   | 絶 縁 抵 抗<br>Insulation Resistance | 10 Megohm MIN.                  |
| 4-3-8       | 温度サイクル<br>Temperature Cycling | コネクタを嵌合させ、-55±3°C に 30分、+105±2°Cに 30分。これを1サイクルとし、5サイクル 繰返す。<br>但し、温度移行時間は 5分以内 とする。<br>試験後1~2時間 室温に放置する。<br>(JIS C60068-2-14)<br><br>Mate connectors and subject to the following conditions for 5 cycles. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>5 cycles of :<br>a) - 55±3°C            30 minutes<br>b) + 105±2°C        30 minutes<br>(JIS C60068-2-14) | 外 観<br>Appearance                | 異常無きこと<br>No Damage             |
|             |                               |   | 接 触 抵 抗<br>Contact Resistance    | 40 milliohm MAX.                |

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|-------------|--------------------------------|---|-------------------------------|---------------------|
| 4-3-9       | 塩水噴霧<br>Salt Spray             | コネクタを嵌合させ、35±2°Cにて5±1%重量比の塩水を48±4時間噴霧し、試験後常温で水洗いした後、室温で乾燥させる。<br>(JIS C60068-2-11/MIL-STD-202 試験法101)<br><br>Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water, after which the specified measurements shall be performed.<br>NaCl solution<br>Concentration : 5±1 %<br>Spray time : 48±4 hours<br>Ambient temperature : 35±2 °C<br>(JIS 60068-2-11/MIL-STD-202 Method 101) | 外 観<br>Appearance             | 異常無きこと<br>No Damage |
|             |                                |   | 接 触 抵 抗<br>Contact Resistance | 40 milliohm MAX.    |
| 4-3-10      | 耐亜硫酸ガス<br>SO <sub>2</sub> Gas  | コネクタを嵌合させ、40±2°Cにて50±5ppmの亜硫酸ガス中に24時間放置する。<br><br>Mated connectors and expose to the conditions of 50±5ppm SO <sub>2</sub> gas ambient temperature 40±2°C for 24 hours.   | 外 観<br>Appearance             | 異常無きこと<br>No Damage |
|             |                                |   | 接 触 抵 抗<br>Contact Resistance | 40 milliohm MAX.    |
| 4-3-11      | 耐アンモニア性<br>NH <sub>3</sub> Gas | コネクタを嵌合させ、濃度28%のアンモニア水を入れた容器中に40分間放置する。<br>(1Lに対して25mLの割合)<br>Mated connectors and expose to the conditions of NH <sub>3</sub> gas evaporating from 28% NH <sub>3</sub> solution for 40 minutes.<br>(Rate is 25ml per 1L)   | 外 観<br>Appearance             | 異常無きこと<br>No Damage |
|             |                                |   | 接 触 抵 抗<br>Contact Resistance | 40 milliohm MAX.    |

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SMT CONNECTOR

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|-------------|--|---|--------------------------|---|
| 4-3-12      | はんだ付け性<br>Solderability                      | ターミナルまたはピンをフラックスに浸し、端子先端より0.5mm迄、<br>245±3°Cのはんだに3±0.5秒浸す。<br>Dip terminal or pin into flux, and immerse the area up to 0.5mm from the tip of terminal into solder molten at 245±3°C for 3±0.5 sec.   | 濡れ性<br>Solder<br>Wetting | ピンホールや隙間なく浸漬面積の95%以上<br>95% of immersed area must show no voids, pin holes. |
| 4-3-13      | はんだ耐熱性<br>Resistance<br>To Soldering<br>Heat | <u>赤外線リフロー時</u><br>(Reflow by IR Reflow Machine)<br>第6項の推奨温度プロファイル条件にてリフローを行う。<br>Using the reflow profile condition below paragraph 6, the product was reflowed.   | 外 観<br>Appearance        | 端子ガタ、割れ等<br>異常なきこと<br>No Damage   |
|             |  | <u>手はんだ時</u><br>(Reflow by Manual Soldering iron)<br>端子先端、金具先端より0.5mmの位置まで、370~400°Cのはんだゴテにて最大5秒加熱する。但し、異常な加圧のないこと。<br>Using a soldering iron (350 ± 10°C for 5 seconds MAX.) heat up the area 0.5mm from the tip of the solder tails and fitting nails. However, do not apply excessive pressure to either the terminals or fitting nails. |                          |   |

( ) : 参考規格 Reference Standard  
{ } : 参考単位 Reference Unit

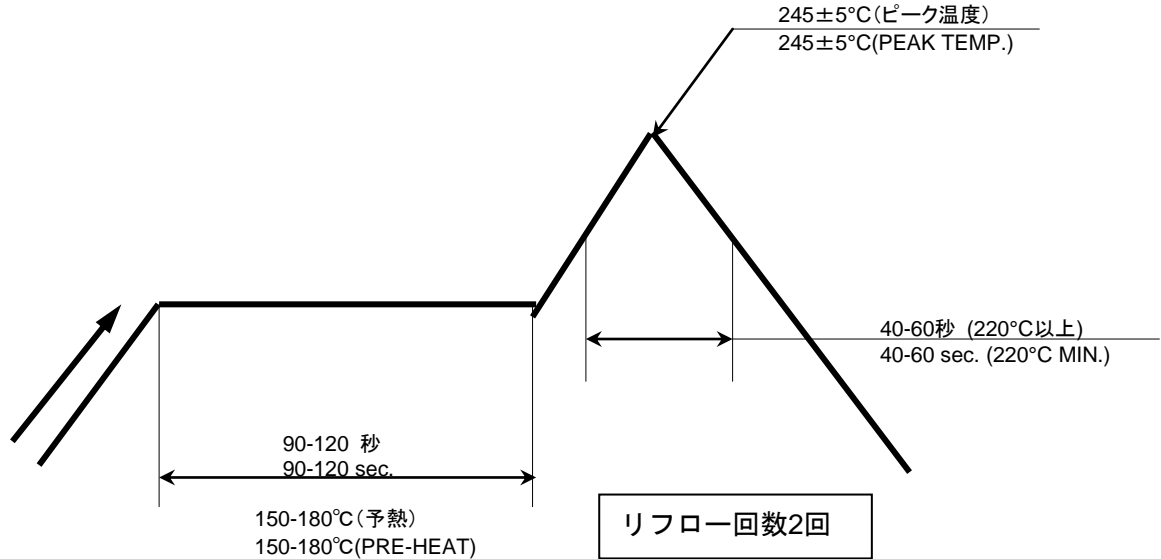
**【5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS】**

**5-1. 製品寸法及び材質 Dimensions and materials of product.**

図面参照 Refer to the drawing.

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【6. リフロー条件 REFLOW CONDITION】



温度条件グラフ  
(温度は基板/パターン面)  
TEMPERATURE CONDITION GRAPH  
(TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

注記;本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので、  
事前にリフロー評価の確認をお願い致します。  
また吸湿などの前処理は行わないで下さい。

NOTE ; Please check the reflow soldering condition by your own devices beforehand.  
Because the condition changes by the soldering devices, P.C.Boards, and so on.  
No moisture treatment before reflow process.

【7. 環境指令への適合 COMPLIANCE WITH ENVIRONMENTAL DIRECTIVE】

- 1. ELV及びRoHS適合品  
ELV and RoHS Compliant

【8. 取り扱いの注意事項 INSTRUCTION UPON USAGE】

- 1. 防湿梱包開封後は防湿効果を失うため、すみやかにご使用下さい。効果維持を考慮し、開梱後の使用目安は48時間以内です。  
Please use it promptly after opening a packing. The recommendation is within at 48 hours.

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【9. 挿入力及び抜去力 INSERTION / WITHDRAWAL FORCE】

| 極数<br>No. of<br>CKT. | 単位<br>Unit   | 挿入力(最大値)<br>Insertion force (MAX.) |                 |                 | 抜去力(最小値)<br>Withdrawal force (MIN.) |                 |                 |
|----------------------|--------------|------------------------------------|-----------------|-----------------|-------------------------------------|-----------------|-----------------|
|                      |              | 初回<br>1st                          | 6回目<br>6th      | 30回目<br>30th    | 初回<br>1st                           | 6回目<br>6th      | 30回目<br>30th    |
| 2                    | N<br>{ kgf } | 19.6<br>{ 2.0 }                    | 17.6<br>{ 1.8 } | 15.6<br>{ 1.6 } | 2.8<br>{ 0.28 }                     | 2.3<br>{ 0.23 } | 1.8<br>{ 0.18 } |
| 3                    | N<br>{ kgf } | 24.5<br>{ 2.5 }                    | 22.5<br>{ 2.3 } | 20.5<br>{ 2.1 } | 3.0<br>{ 0.30 }                     | 2.5<br>{ 0.25 } | 2.0<br>{ 0.20 } |
| 4                    | N<br>{ kgf } | 29.4<br>{ 3.0 }                    | 27.4<br>{ 2.8 } | 25.4<br>{ 2.6 } | 3.3<br>{ 0.33 }                     | 2.8<br>{ 0.28 } | 2.3<br>{ 0.23 } |
| 5                    | N<br>{ kgf } | 34.3<br>{ 3.5 }                    | 32.3<br>{ 3.3 } | 30.3<br>{ 3.1 } | 3.8<br>{ 0.38 }                     | 3.3<br>{ 0.33 } | 2.8<br>{ 0.28 } |
| 6                    | N<br>{ kgf } | 39.2<br>{ 4.0 }                    | 37.2<br>{ 3.8 } | 35.2<br>{ 3.6 } | 4.3<br>{ 0.43 }                     | 3.8<br>{ 0.38 } | 3.3<br>{ 0.33 } |
| 7                    | N<br>{ kgf } | 44.1<br>{ 4.5 }                    | 42.1<br>{ 4.3 } | 40.1<br>{ 4.1 } | 4.7<br>{ 0.48 }                     | 4.3<br>{ 0.43 } | 3.8<br>{ 0.38 } |
| 8                    | N<br>{ kgf } | 49.0<br>{ 5.0 }                    | 47.0<br>{ 4.8 } | 45.0<br>{ 4.6 } | 5.2<br>{ 0.53 }                     | 4.7<br>{ 0.48 } | 4.3<br>{ 0.43 } |
| 9                    | N<br>{ kgf } | 53.9<br>{ 5.5 }                    | 51.9<br>{ 5.3 } | 49.9<br>{ 5.1 } | 5.5<br>{ 0.56 }                     | 5.0<br>{ 0.51 } | 4.5<br>{ 0.46 } |
| 10                   | N<br>{ kgf } | 58.8<br>{ 6.0 }                    | 56.8<br>{ 5.8 } | 54.8<br>{ 5.6 } | 5.8<br>{ 0.59 }                     | 5.3<br>{ 0.54 } | 4.8<br>{ 0.49 } |
| 11                   | N<br>{ kgf } | 63.7<br>{ 6.5 }                    | 61.7<br>{ 6.3 } | 59.7<br>{ 6.1 } | 6.1<br>{ 0.62 }                     | 5.6<br>{ 0.57 } | 5.1<br>{ 0.52 } |
| 12                   | N<br>{ kgf } | 68.6<br>{ 7.0 }                    | 66.6<br>{ 6.8 } | 64.6<br>{ 6.6 } | 6.4<br>{ 0.65 }                     | 5.9<br>{ 0.60 } | 5.4<br>{ 0.55 } |
| 13                   | N<br>{ kgf } | 73.5<br>{ 7.5 }                    | 71.5<br>{ 7.3 } | 69.5<br>{ 7.1 } | 6.7<br>{ 0.68 }                     | 6.2<br>{ 0.63 } | 5.7<br>{ 0.58 } |
| 14                   | N<br>{ kgf } | 78.4<br>{ 8.0 }                    | 76.4<br>{ 7.8 } | 74.4<br>{ 7.6 } | 7.0<br>{ 0.71 }                     | 6.5<br>{ 0.66 } | 6.0<br>{ 0.61 } |
| 15                   | N<br>{ kgf } | 83.3<br>{ 8.5 }                    | 81.3<br>{ 8.3 } | 79.3<br>{ 8.1 } | 7.3<br>{ 0.74 }                     | 6.8<br>{ 0.69 } | 6.3<br>{ 0.64 } |
| 17                   | N<br>{ kgf } | 93.1<br>{ 9.5 }                    | 91.2<br>{ 9.3 } | 89.2<br>{ 9.1 } | 7.9<br>{ 0.8 }                      | 7.4<br>{ 0.75 } | 6.9<br>{ 0.70 } |

|  |                   |  |
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【10. 圧着端子取り扱い上の注意事項 INSTRUCTION UPON USAGE OF CRIMP TERMINAL】

1. 保管する場合には、外装カートン表示に従って保管願います。縦置き又は、天地逆に保管すると巻き緩みの原因になります。  
When storing crimp terminal, please follow the view of outer carton. Do not store in an upright position or upside down. It could loosen the terminal.

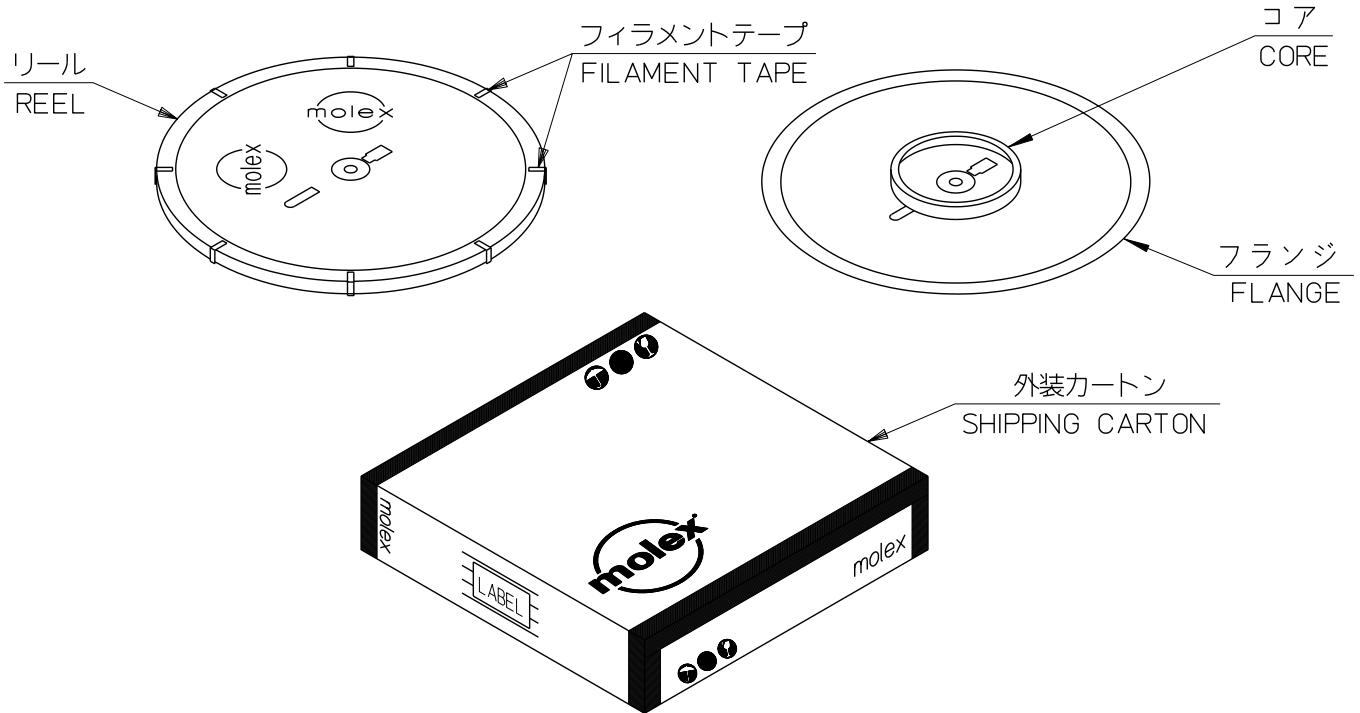


図 1 端子梱包に関する各部名称  
FIG.1. NOMENCLATURE FOR THE TERMINAL PACKAGING

2. 保管環境に著しい高温・湿度がある場合、端子表面層に錆等の影響を及ぼす事がありますのでご注意ください。  
When storing the terminal in the significant temperature or, humidity, may be affected at the terminal surface.

|  |                   |  |                   |
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3. 輸送、運搬時、カートン内リール数が規定梱包数量に満たない場合には、リールに衝撃を与えぬ様に緩衝材を入れガタつき防止を行って下さい。  
When number of reel in carton less than the prescribed quantity, prevent looseness with adding the cushion, during transport, conveyance.

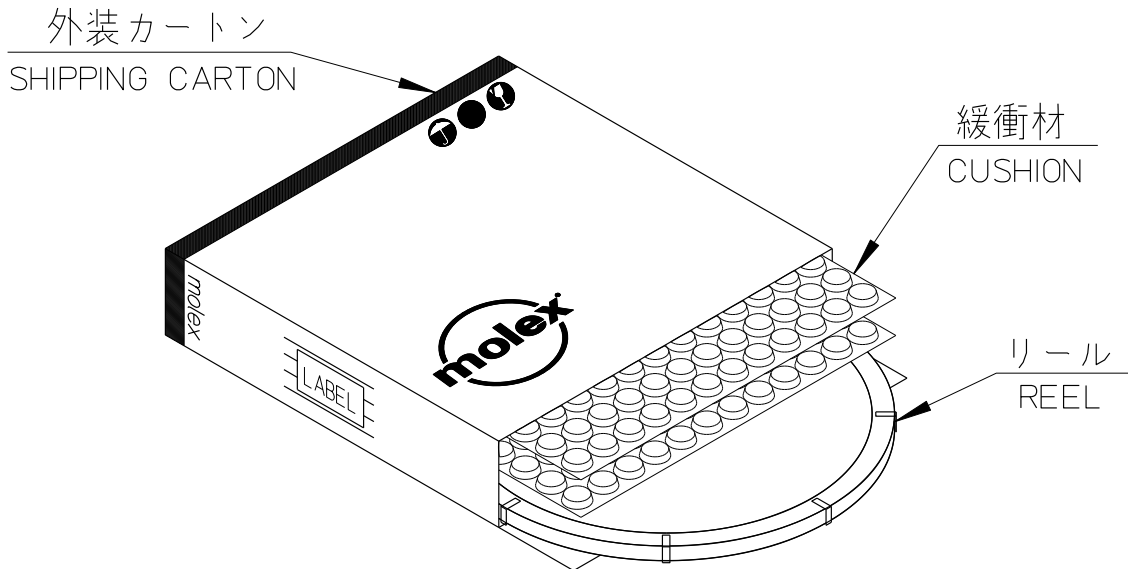


図2 カートン内リール数が規定梱包数量に満たない場合の梱包方法  
FIG.2 PACKAGING METHOD, IN CASE OF NUMBER OF REEL  
IN CARTON LESS THAN THE PRESCRIBED QUANTITY

|  |                   |  |
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4. カートンからリールを取り出す際は、両側フランジを持ち取り出して下さい。片面だけを掴んだ場合端子自重によりコア部からフランジ面が剥がれる恐れがあります。  
 When removing the reel from the carton, please remove with holding the flange on both sides. Do not grab only one side. It could detach the flange from the core.

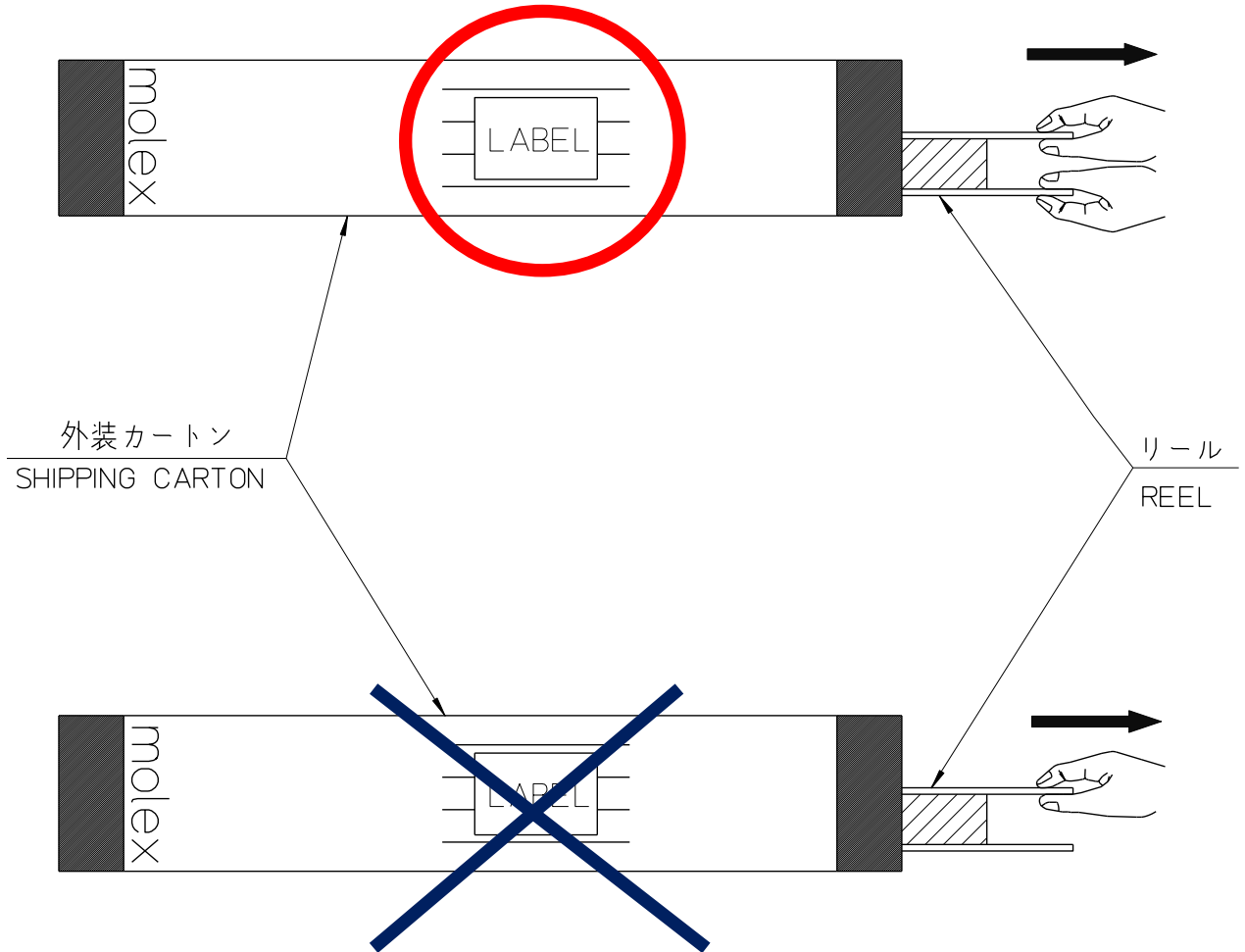
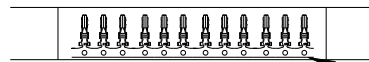
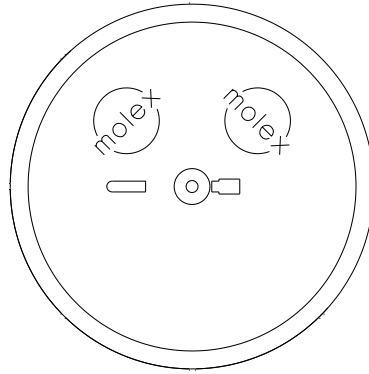


図3 リールの取り出し方法  
 FIG.3 METHOD OF REMOVING THE REEL FROM THE CARTON

|  |                   |  |
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5. カートンよりリールを取り出し保管される場合には、キャリア側を下側にし保管願ます。  
 キャリア側を上にし、保管されますと端子自重により巻き緩みが発生する恐れがあります。  
 When storing the terminal with remove the reel from the carton, please keep carrier down side. Do not keep carrier up side. It could loosen the terminal.



キャリア側を下  
 CARRIER SIDE ORIENTED DOWNWARD

図4リール保管時の向き  
 FIG.4 DIRECTION OF THE REEL STORAGE

6. 圧着機へリールを長時間掛けた状態でいますと、端子自重により巻き緩みが発生する恐れがあります。  
 ご使用にならない場合には、中間紙で端子全周を2~3周巻いた後、巻き緩みが生じない様、中間紙先端、フランジ間のテープ止めをし、キャリア側を下にし保管願ます。  
 Do not put the reel in the crimping machine for long period. It could loosen the terminal. When it is not used, after rolling interleaf twice, or three times into terminal all around, please keep carrier down side, with taping tip of the interleaf and flange.
7. 圧着仕様を満足する為に、当社推奨圧着機のご使用をお願い致します。  
 In order to meet the crimp specification, please use our recommended crimping machine.
8. 外装カートン組立及び、中間紙繋ぎにステープル(ホチキス)は、使用しないで下さい。  
 Stapler prohibited in whole area with outer carton assembly, linking the interleaf .

|  |                   |  |
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**molex****PRODUCT SPECIFICATION**

LANGUAGE

JAPANESE  
ENGLISH

| REV. | REV. RECORD | DATE       | ECN NO.    | WRITTEN BY : | CHECKED BY : |
|------|-------------|------------|------------|--------------|--------------|
| A    | RELEASED    | 2004/02/05 | J2004-2276 | E.SUZUKI     | K.TOJO       |
| B    | REVISED     | 2004/03/10 | J2004-3002 | E.SUZUKI     | K.TOJO       |
| C    | REVISED     | 2004/03/29 | J2004-3401 | E.SUZUKI     | K.TOJO       |
| D    | REVISED     | 2004/07/21 | J2005-0243 | N.AIDA       | K.TOJO       |
| E    | REVISED     | 2004/12/06 | J2005-1671 | E.SUZUKI     | K.TOJO       |
| F    | REVISED     | 2005/02/15 | J2005-2371 | E.SUZUKI     | K.TOJO       |
| G    | REVISED     | 2005/04/19 | J2005-3130 | N.AIDA       | K.TOYODA     |
| H    | REVISED     | 2006/01/18 | J2006-2296 | N.AIDA       | K.TOYODA     |
| J    | REVISED     | 2007/07/02 | J2008-0007 | K.SAITO      | T.HARUYAMA   |
| K    | REVISED     | 2007/05/27 | J2008-0078 | Y.AOYAGI     | H.MATSUMOTO  |
| L    | REVISED     | 2009/01/06 | J2009-1681 | M.TAKAZONO   | H.MATSUMOTO  |
| M    | REVISED     | 2011/10/14 | J2012-0524 | R.HORI       | K.ASAKAWA    |
| N    | REVISED     | 2012/03/09 | J2012-1209 | R.HORI       | K.ASAKAWA    |
| P    | REVISED     | 2016/08/17 | 107484     | Q.HE         | S.AKIYAMA    |
| R    | REVISED     | 2016/08/18 | 107594     | Q.HE         | S.AKIYAMA    |
| T    | REVISED     | 2016/12/27 | 110641     | K.OMORI      | S.AKIYAMA    |
|      |             |            |            |              |              |
|      |             |            |            |              |              |

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